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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	XCore
Core Size	32-Bit 10-Core
Speed	1000MIPS
Connectivity	Configurable
Peripherals	-
Number of I/O	90
Program Memory Size	128KB (32K x 32)
Program Memory Type	SRAM
EEPROM Size	-
RAM Size	•
Voltage - Supply (Vcc/Vdd)	0.90V ~ 5.5V
Data Converters	A/D 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	217-LFBGA
Supplier Device Package	217-FBGA (16x16)
Purchase URL	https://www.e-xfl.com/product-detail/xmos/xs1-a10a-128-fb217-i10

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

2 XS1-A10A-128-FB217 Features

► Multicore Microcontroller with Advanced Multi-Core RISC Architecture

- 10 real-time logical cores on 2 xCORE tiles
- Cores share up to 1000 MIPS
- Each logical core has:
 - Guaranteed throughput of between 1/4 and 1/5 of tile MIPS
 - 16x32bit dedicated registers
- 159 high-density 16/32-bit instructions
 - All have single clock-cycle execution (except for divide)
 - 32x32 ${\rightarrow}64\text{-bit}$ MAC instructions for DSP, arithmetic and user-definable cryptographic functions
- ▶ 12b 1MSPS 8-channel SAR Analog-to-Digital Converter
- ► 1 x LDO
- > 2 x DC-DC converters and Power Management Unit
- Watchdog Timer
- Onchip clocks/oscillators
 - Crystal oscillator
 - 20MHz/31kHz silicon oscillators
- ► Programmable I/O
 - 90 general-purpose I/O pins, configurable as input or output
 - Up to 32 x 1bit port, 12 x 4bit port, 8 x 8bit port, 4 x 16bit port
 4 xCONNECT links
 - Port sampling rates of up to 60 MHz with respect to an external clock
 - 64 channel ends for communication with other cores, on or off-chip

Memory

- 128KB internal single-cycle SRAM (max 64KB per tile) for code and data storage
- 16KB internal OTP (max 8KB per tile) for application boot code
- 128 bytes Deep Sleep Memory

Hardware resources

- 12 clock blocks (6 per tile)
- 20 timers (10 per tile)
- 8 locks (4 per tile)
- JTAG Module for On-Chip Debug
- Security Features
 - Programming lock disables debug and prevents read-back of memory contents
 - AES bootloader ensures secrecy of IP held on external flash memory

Ambient Temperature Range

- Commercial qualification: 0°C to 70°C
- Industrial qualification: -40 °C to 85 °C
- Speed Grade
 - 10: 1000 MIPS
 - 8: 800 MIPS
- Power Consumption (typical)
 - 600 mW at 500 MHz (typical)
 - Sleep Mode: 500 µW
- > 217-pin FBGA package 0.8 mm pitch

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6 Product Overview

The XS1-A10A-128-FB217 comprises a digital and an analog node, as shown in Figure 3. The digital node comprises an xCORE Tile, a Switch, and a PLL (Phase-locked-loop). The analog node comprises a multi-channel ADC (Analog to Digital Converter), deep sleep memory, an oscillator, a real-time counter, and power supply control.



All communication between the digital and analog node takes place over a link that is connected to the Switch of the digital node. As such, the analog node can be controlled from any node on the system. The analog functions can be configured using a set of node configuration registers, and a set of registers for each of the peripherals.

The device can be programmed using high-level languages such as C/C++ and the XMOS-originated XC language, which provides extensions to C that simplify the control over concurrency, I/O and timing, or low-level assembler.

6.1 XCore Tile

The xCORE Tile is a flexible multicore microcontroller component with tightly integrated I/O and on-chip memory. The tile contains multiple logical cores that run simultaneously, each of which is guaranteed a slice of processing power and can execute computational code, control software and I/O interfaces. The logical cores use channels to exchange data within a tile or across tiles. The tiles are connected via an integrated switch network, called xCONNECT, which uses a

13.1 DC-DC

XS1-A10A-128-FB217 devices include two DC-DC buck converters which can be configured to take input voltages between 3.3-5V power supply and output circuit voltages (nominally 1.8V and 1.0V) required by the analog peripherals and digital node.

13.2 Power mode controller

The device transitions through multiple states during the power-up and powerdown process.



The device is quiescent in the ASLEEP state, and is running in the AWAKE state. The other states allow a controlled transition between AWAKE and ASLEEP.

A transition from AWAKE state to ASLEEP state is instigated by a write to the general control register. Sleep requests must only be made in the AWAKE state.

A transition from the ASLEEP state into the AWAKE state is instigated by a wakeup request triggered by an input, or a timer. The device only responds to a wakeup stimulus in the ASLEEP state. If wakeup stimulus occurs whilst transitioning from AWAKE to ASLEEP, the appropriate response occurs when the ASLEEP state is reached.

Configuration is through a set of registers documented in Appendix J.

The power supplies must be brought up monotonically and input voltages must not exceed specification at any time.

The VDDIO supply to the XS1-A10A-128-FB217 requires a 100nF X5R or X7R ceramic decoupling capacitor placed as close as possible to the supply pins. VDDIO_OUT is the switched IO supply; it is only supplied when the chip is AWAKE. This pin can be used to provide extra decoupling, or it can be used to switch other devices off during sleep mode, for example a SPI flash. No more than 240 mA should be drawn on VDDIO at any time: this includes any supply sourced statically (e.g., driving a LED from a GPIO pin), any dynamic power consumption (e.g., toggling a GPIO pin at a high frequency) and any devices powered through VDDIO_OUT.

If the ADC Is used, it requires a 100nF X5R or X7R ceramic decoupling capacitor placed as close as possible to the AVDD pin. Care should be taken to minimize noise on these inputs, and if necessary an extra 10uF decoupling capacitor and ferrite bead can be used to remove noise from this supply.

The crystal oscillator requires careful routing of the XI / XO nodes as these are high impedance and very noise sensitive. Hence, the traces should be as wide and short as possible, and routed over a continuous ground plane. They should not be routed near noisy supply lines or clocks. The device has a load capacitance of 18pF for the crystal. Care must be taken, so that the inductance and resistance of the ground returns from the capacitors to the ground of the device is minimized.

15.1 Land patterns and solder stencils

The land pattern recommendations in this document are based on a RoHS compliant process and derived, where possible, from the nominal *Generic Requirements for Surface Mount Design and Land Pattern Standards* IPC-7351B specifications. This standard aims to achieve desired targets of heel, toe and side fillets for solder-joints.

Solder paste and ground via recommendations are based on our engineering and development kit board production. They have been found to work and optimized as appropriate to achieve a high yield. These factors should be taken into account during design and manufacturing of the PCB.

The following land patterns and solder paste contains recommendations. Final land pattern and solder paste decisions are the responsibility of the customer. These should be tuned during manufacture to suit the manufacturing process.

The package is a 217 pin Fine Ball Grid Array package on a 0.8mm pitch with 0.4mm balls.

An example land pattern is shown in Figure 20.

Pad widths and spacings are such that solder mask can still be applied between the pads using standard design rules. This is highly recommended to reduce solder shorts.

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17 DC and Switching Characteristics

Symbol	Parameter	MIN	ТҮР	MAX	UNITS	Notes
VSLIP	Power Supply (3.3V Mode)	3.00	3.30	3.60	V	
v301	Power Supply (5V Mode)	4.50	5.00	5.50	V	
VDDIO	I/O supply voltage	3.00	3.30	3.60	V	
AVDD	Analog Supply and Reference Voltage	3.00	3.30	3.60	V	
Cl	xCORE Tile I/O load capacitance			25	рF	
Та	Ambient operating temperature (Commercial)	0		70	°C	
	Ambient operating temperature (Industrial)	-40		85	°C	
Tj	Junction temperature			125	°C	
Tstg	Storage temperature	-65		150	°C	

17.1 Operating Conditions

Figure 24: Operating conditions

17.2 DC1 Characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
VDDCORE	Tile Supply Voltage	0.90	1.00	1.10	V	
V(RIPPLE)	Ripple Voltage (peak to peak)		10	40	mV	
V(ACC)	Voltage Accuracy	-5		5	%	A
F(S)	Switching Frequency		1		MHz	
F(SVAR)	Variation in Switching Frequency	-10		10	%	
Effic	Efficiency		80		%	
PGT(HIGH)	Powergood Threshold (High)		95		%/VDDCORE	
PGT(LOW)	Powergood Threshold (Low)		80		%/VDDCORE	

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Figure 25: DC1 characteristics

A If supplied externally.

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
VDD1V8	1V8 Supply Voltage		1.80		V	
V(RIPPLE)	Ripple Voltage (peak to peak)		10	40	mV	
V(ACC)	Voltage Accuracy	-5		5	%	A
F(S)	Switching Frequency		1		MHz	
F(SVAR)	Variation in Switching Frequency	-10		10	%	
Effic	Efficiency		80		%	
PGT(HIGH)	Powergood Threshold (High)		95		%/VDD1V8	
PGT(LOW)	Powergood Threshold (Low)		80		%/VDD1V8	

17.3 DC2 Characteristics

Figure 26: DC2 characteristics

A If supplied externally.

17.4 ADC Characteristics

Symbol	Parameter	MIN	TYP	MAX	UNITS	Notes
N	Resolution		12		bits	
Fs	Conversion Speed			1	MSPS	
Nch	Number of Channels		8			
Vin	Input Range	0		AVDD	V	
DNL	Differential Non Linearity	-1		1.5	LSB	
INL	Integral Non Linearity	-4		4	LSB	
E(GAIN)	Gain Error	-10		10	LSB	
E(OFFSET)	Offset Error	-3		3	mV	
T(PWRUP)	Power time for ADC Clock Fclk			7	1/Fclk	
ENOB	Effective Number of bits		10			

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Figure 27: ADC characteristics A write message comprises the following:

control-token	24-bit response	16-bit	32-bit	control-token
192	channel-end identifier	register number	data	1

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

 control-token
 24-bit response
 16-bit
 control-token

 193
 channel-end identifier
 register number
 1

The response to the read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

A.3 Accessing digital and analogue node configuration registers

Node configuration registers can be accessed through the interconnect using the functions write_node_config_reg(device, ...) and read_node_config_reg(device, \rightarrow ...), where device is the name of the node. These functions implement the protocols described below.

Instead of using the functions above, a channel-end can be allocated to communicate with the node configuration registers. The destination of the channel-end should be set to 0xnnnnC30C where nnnn is the node-identifier.

A write message comprises the following:

control-token	24-bit response	16-bit	32-bit	control-token
192	channel-end identifier	register number	data	1

The response to a write message comprises either control tokens 3 and 1 (for success), or control tokens 4 and 1 (for failure).

A read message comprises the following:

control-token	24-bit response	16-bit	control-token
193	channel-end identifier	register number	1

The response to a read message comprises either control token 3, 32-bit of data, and control-token 1 (for success), or control tokens 4 and 1 (for failure).

A.4 Accessing a register of an analogue peripheral

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Peripheral registers can be accessed through the interconnect using the functions write_periph_32(device, peripheral, ...), read_periph_32(device, peripheral, ...) \rightarrow , write_periph_8(device, peripheral, ...), and read_periph_8(device, peripheral \rightarrow , ...); where device is the name of the analogue device, and peripheral is the number of the peripheral. These functions implement the protocols described below.

Bits	Perm	Init	Description
31:18	RO	-	Reserved
17:16	DRW		If the debug interrupt was caused by a hardware breakpoint or hardware watchpoint, this field contains the number of the breakpoint or watchpoint. If multiple breakpoints or watch- points trigger at once, the lowest number is taken.
15:8	DRW		If the debug interrupt was caused by a logical core, this field contains the number of that core. Otherwise this field is 0.
7:3	RO	-	Reserved
2:0	DRW	0	Indicates the cause of the debug interrupt 1: Host initiated a debug interrupt through JTAG 2: Program executed a DCALL instruction 3: Instruction breakpoint 4: Data watch point 5: Resource watch point

0x15: Debug interrupt type

B.17 Debug interrupt data: 0x16

On a data watchpoint, this register contains the effective address of the memory operation that triggered the debugger. On a resource watchpoint, it countains the resource identifier.

0x16 Debug interrupt data

ox16: ebug	Bits	Perm	Init	Description
data	31:0	DRW		Value.

B.18 Debug core control: 0x18

This register enables the debugger to temporarily disable logical cores. When returning from the debug interrupts, the cores set in this register will not execute. This enables single stepping to be implemented.

0x18: Debug core control

Bits	Perm	Init	Description
31:8	RO	-	Reserved
7:0	DRW		1-hot vector defining which logical cores are stopped when not in debug mode. Every bit which is set prevents the respective logical core from running.

0x50 .. 0x53: Data watchpoint address 1

Data point	Bits	Perm	Init	Description
ess 1	31:0	DRW		Value.

B.23 Data watchpoint address 2: 0x60 .. 0x63

This set of registers contains the second address for the four data watchpoints.

0x60 .. 0x63: Data watchpoint address 2

ia nt	Bits	Perm	Init	Description
2	31:0	DRW		Value.

B.24 Data breakpoint control register: 0x70 .. 0x73

This set of registers controls each of the four data watchpoints.

	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
	23:16	DRW	0	A bit for each logical core in the tile allowing the breakpoint to be enabled individually for each logical core.
	15:3	RO	-	Reserved
	2	DRW	0	Set to 1 to enable breakpoints to be triggered on loads. Breakpoints always trigger on stores.
3: a it	1	DRW	0	By default, data watchpoints trigger if memory in the range [Address1Address2] is accessed (the range is inclusive of Address1 and Address2). If set to 1, data watchpoints trigger if memory outside the range (Address2Address1) is accessed (the range is exclusive of Address2 and Address1).
r	0	DRW	0	When 1 the instruction breakpoint is enabled.

0x70 .. 0x73: Data breakpoint control register

B.25 Resources breakpoint mask: 0x80 .. 0x83

This set of registers contains the mask for the four resource watchpoints.

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C.2 xCORE Tile description 1: 0x01

This register describes the number of logical cores, synchronisers, locks and channel ends available on this xCORE tile.

Bits	Perm	Init	Description
31:24	RO		Number of channel ends.
23:16	RO		Number of locks.
15:8	RO		Number of synchronisers.
7:0	RO	-	Reserved

C.3 xCORE Tile description 2: 0x02

This register describes the number of timers and clock blocks available on this xCORE tile.

0x02 xCORE Tile description 2

0x01: xCORE Tile description 1

	Bits	Perm	Init	Description
.	31:16	RO	-	Reserved
 2	15:8	RO		Number of clock blocks.
2	7:0	RO		Number of timers.

C.4 Control PSwitch permissions to debug registers: 0x04

This register can be used to control whether the debug registers (marked with permission CRW) are accessible through the tile configuration registers. When this bit is set, write -access to those registers is disabled, preventing debugging of the xCORE tile over the interconnect.

0x04: Control PSwitch permissions to debug registers

Bits	Perm	Init	Description
31:1	RO	-	Reserved
0	CRW		Set to 1 to restrict PSwitch access to all CRW marked registers to become read-only rather than read-write.

C.5 Cause debug interrupts: 0x05

This register can be used to raise a debug interrupt in this xCORE tile.

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D Digital Node Configuration

The digital node control registers can be accessed using configuration reads and writes (use write_node_config_reg(device, ...) and read_node_config_reg(device, ...) for reads and writes).

Number	Perm	Description
0x00	RO	Device identification
0x01	RO	System switch description
0x04	RW	Switch configuration
0x05	RW	Switch node identifier
0x06	RW	PLL settings
0x07	RW	System switch clock divider
0x08	RW	Reference clock
0x0C	RW	Directions 0-7
0x0D	RW	Directions 8-15
0x10	RW	DEBUG_N configuration
0x1F	RO	Debug source
0x20 0x27	RW	Link status, direction, and network
0x40 0x43	RW	PLink status and network
0x80 0x87	RW	Link configuration and initialization
0xA0 0xA7	RW	Static link configuration

Figure 43: Summary

D.1 Device identification: 0x00

This register contains version and revision identifiers and the mode-pins as sampled at boot-time.

	Bits	Perm	Init	Description
	31:24	RO	0x00	Chip identifier.
0×00:	23:16	RO		Sampled values of pins MODE0, MODE1, on reset.
Device	15:8	RO		SSwitch revision.
identification	7:0	RO		SSwitch version.

D.2 System switch description: 0x01

This register specifies the number of processors and links that are connected to this switch.

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	Bits	Perm	Init	Description
	31:24	RO	-	Reserved
0x01:	23:16	RO		Number of links on the switch.
switch	15:8	RO		Number of cores that are connected to this switch.
description	7:0	RO		Number of links per processor.

D.3 Switch configuration: 0x04

This register enables the setting of two security modes (that disable updates to the PLL or any other registers) and the header-mode.

Bits	Perm	Init	Description
31	RO	0	Set to 1 to disable any write access to the configuration registers in this switch.
30:9	RO	-	Reserved
8	RO	0	Set to 1 to disable updates to the PLL configuration register.
7:1	RO	-	Reserved
0	RO	0	Header mode. Set to 1 to enable 1-byte headers. This must be performed on all nodes in the system.

0x04: Switch configuration

D.4 Switch node identifier: 0x05

This register contains the node identifier.

0x05 Switch node identifier

	Bits	Perm	Init	Description
•	31:16	RO	-	Reserved
: r	15:0	RW	0	The unique 16-bit ID of this node. This ID is matched most- significant-bit first with incoming messages for routing pur- poses.

D.5 PLL settings: 0x06

An on-chip PLL multiplies the input clock up to a higher frequency clock, used to clock the I/O, processor, and switch, see Oscillator. Note: a write to this register will cause the tile to be reset.

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D.11 Debug source: 0x1F

Contains the source of the most recent debug event.

Bits	Perm	Init	Description
31:5	RO	-	Reserved
4	RW		If set, the external DEBUG_N pin is the source of the most recent debug interrupt.
3:1	RO	-	Reserved
0	RW		If set, the xCORE Tile is the source of the most recent debug interrupt.

0x1F: Debug source

D.12 Link status, direction, and network: 0x20 .. 0x27

These registers contain status information for low level debugging (read-only), the network number that each link belongs to, and the direction that each link is part of. The registers control links C, D, A, B, G, H, E, and F in that order.

	Bits	Perm	Init	Description
:	31:26	RO	-	Reserved
	25:24	RO		If this link is currently routing data into the switch, this field specifies the type of link that the data is routed to: 0: plink 1: external link 2: internal control link
2	23:16	RO	0	If the link is routing data into the switch, this field specifies the destination link number to which all tokens are sent.
•	15:12	RO	-	Reserved
	11:8	RW	0	The direction that this this link is associated with; set for rout- ing.
	7:6	RO	-	Reserved
	5:4	RW	0	Determines the network to which this link belongs, set for quality of service.
	3	RO	-	Reserved
	2	RO	0	Set to 1 if the current packet is junk and being thrown away. A packet is considered junk if, for example, it is not routable.
	1	RO	0	Set to 1 if the switch is routing data into the link, and if a route exists from another link.
	0	RO	0	Set to 1 if the link is routing data into the switch, and if a route is created to another link on the switch.

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0x20 .. 0x27: Link status, direction, and network

D.13 PLink status and network: 0x40 .. 0x43

These registers contain status information and the network number that each processor-link belongs to.

Bits	Perm	Init	Description
31:26	RO	-	Reserved
25:24	RO		If this link is currently routing data into the switch, this field specifies the type of link that the data is routed to: 0: plink 1: external link 2: internal control link
23:16	RO	0	If the link is routing data into the switch, this field specifies the destination link number to which all tokens are sent.
15:6	RO	-	Reserved
5:4	RW	0	Determines the network to which this link belongs, set for quality of service.
3	RO	-	Reserved
2	RO	0	Set to 1 if the current packet is junk and being thrown away. A packet is considered junk if, for example, it is not routable.
1	RO	0	Set to 1 if the switch is routing data into the link, and if a route exists from another link.
0	RO	0	Set to 1 if the link is routing data into the switch, and if a route is created to another link on the switch.

0x40 .. 0x43: PLink status and network

D.14 Link configuration and initialization: 0x80 .. 0x87

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These registers contain configuration and debugging information specific to external links. The link speed and width can be set, the link can be initialized, and the link status can be monitored. The registers control links C, D, A, B, G, H, E, and F in that order.

Bits	Perm	Init	Description
31:28	RO	-	Reserved
27	RO	0	Set to 1 on error: an RX buffer overflow or illegal token encoding has been received. This bit clears on reading.
26	RO	0	1 if this end of the link has issued credit to allow the remote end to transmit.
25	RO	0	1 if this end of the link has credits to allow it to transmit.
24	WO	0	Set to 1 to initialize a half-duplex link. This clears this end of the link's credit and issues a HELLO token; the other side of the link will reply with credits. This bit is self-clearing.
23	WO	0	Set to 1 to reset the receiver. The next symbol that is detected will be assumed to be the first symbol in a token. This bit is self-clearing.
22	RO	-	Reserved
21:11	RW	1	The number of system clocks between two subsequent transi- tions within a token
10:0	RW	1	The number of system clocks between two subsequent transmit tokens.

E.6 Link Control and Status: 0x80

0x80: Link Control and Status

E.7 1 KHz Watchdog Control: 0xD6

The watchdog provides a mechanism to prevent programs from hanging by resetting the xCORE Tile after a pre-set time. The watchdog should be periodically "kicked" by the application, causing the count-down to be restarted. If the watchdog expires, it may be due to a program hanging, for example because of a (transient) hardware issue.

The watchdog timeout is measured in 1 ms clock ticks, meaning that a time between 1 ms and 65 seconds can be set for the timeout. The watchdog timer is only clocked during the AWAKE power state. When writing the timeout value, both the timeout and its one's complement should be written. This reduces the chances of accidentally setting kicking the watchdog. If the written value does not comprise a 16-bit value with a 16-bit one's complement, the request will be NACKed, otherwise an ACK will be sent.

If the watchdog expires, the xCORE Tile is reset.

0xD6:	Bits	Perm	Init	Description
1 KHz	31:16	RO	0	Current value of watchdog timer.
Watchdog Control	15:0	RW	1000	Number of 1kHz cycles after which the watchdog should ex- pire and initiate a system reset.

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I Real time clock Configuration

The *Real time clock* is peripheral 5. The control registers are accessed using 32-bit reads and writes (use write_periph_32(device, 5, ...) and read_periph_32(device, \rightarrow 5, ...) for reads and writes).

	Number	Perm	Description
Figure 48: Summary	0x00	RW	Real time counter least significant 32 bits
	0x04	RW	Real time counter most significant 32 bits

I.1 Real time counter least significant 32 bits: 0x00

This registers contains the lower 32-bits of the real-time counter.

Bits	Perm	Init	Description
31:0	RO	0	Least significant 32 bits of real-time counter.
	Bits 31:0	Bits Perm 31:0 RO	BitsPermInit31:0RO0

I.2 Real time counter most significant 32 bits: 0x04

This registers contains the upper 32-bits of the real-time counter.



J Power control block Configuration

The *Power control block* is peripheral 6. The control registers are accessed using 32-bit reads and writes (use write_periph_32(device, 6, ...) and read_periph_32(\hookrightarrow device, 6, ...) for reads and writes).



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J.5 Power supply states whilst WAKING1: 0x10

This register controls what state the power control block should be in when in the WAKING1 state. It also defines the minimum time that the system shall stay in this state. When the minimum time is expired, the next state is entered if all enabled power supplies are good.

Bits	Perm	Init	Description
31:21	RO	-	Reserved
20:16	RW	16	Log2 number of cycles to stay in this state: 0: 1 clock cycles 1: 2 clock cycles 2: 4 clock cycles 31: 2147483648 clock cycles
15	RO	-	Reserved
14	RW	0	Set to 1 to disable clock to the xCORE Tile.
13:10	RO	-	Reserved
9	RW	0	Sets modulation used by DCDC2: 0: PWM modulation (max 475 mA) 1: PFM modulation (max 50 mA)
8	RW	0	Sets modulation used by DCDC1: 0: PWM modulation (max 700 mA) 1: PFM modulation (max 50 mA)
7:6	RO	-	Reserved
5	RW	1	Set to 1 to enable VOUT6 (IO supply).
4	RW	0	Set to 1 to enable LDO5 (core PLL supply).
3:2	RO	-	Reserved
1	RO	0	Set to 1 to enable DCDC2 (analogue supply).
0	RW	0	Set to 1 to enable DCDC1 (core supply).

0x10: Power supply states whilst WAKING1

J.6 Power supply states whilst WAKING2: 0x14

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This register controls what state the power control block should be in when in the WAKING2 state. It also defines the minimum time that the system shall stay in this state. When the minimum time is expired, the next state is entered if all enabled power supplies are good.

Bits	Perm	Init	Description
31:15	RO	-	Reserved
14	RW	0	Set to 1 to disable clock to the xCORE Tile.
13:10	RO	-	Reserved
9	RW	0	Sets modulation used by DCDC2: 0: PWM modulation (max 475 mA) 1: PFM modulation (max 50 mA)
8	RW	0	Sets modulation used by DCDC1: 0: PWM modulation (max 700 mA) 1: PFM modulation (max 50 mA)
7:6	RO	-	Reserved
5	RW	1	Set to 1 to enable VOUT6 (IO supply).
4	RW	1	Set to 1 to enable LDO5 (core PLL supply).
3:2	RO	-	Reserved
1	RO	1	Set to 1 to enable DCDC2 (analogue supply).
0	RW	1	Set to 1 to enable DCDC1 (core supply).

0x18: Power supply states whilst AWAKE

J.8 Power supply states whilst SLEEPING1: 0x1C

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This register controls what state the power control block should be in when in the SLEEPING1 state. It also defines the time that the system shall stay in this state.

Bits	Perm	Init	Description	
31:30	RO	-	Reserved	
29	RO	0	1 if VOUT6 was enabled in the previous state.	
28	RO	0	1 if LDO5 was enabled in the previous state.	
27:26	RO	-	Reserved	
25	RO	1	1 if DCDC2 was enabled in the previous state.	
24	RO	0	1 if DCDC1 was enabled in the previous state.	
23:19	RO	-	Reserved	
18:16	RO		Current state of the power sequence state machine 0: Reset 1: Asleep 2: Waking 1 3: Waking 2 4: Awake Wait 5: Awake 6: Sleeping 1 7: Sleeping 2	
15	RO	-	Reserved	
14	RO	0	Set to 1 to disable clock to the xCORE Tile.	
13:10	RO	-	Reserved	
9	RO	0	Sets modulation used by DCDC2: 0: PWM modulation (max 475 mA) 1: PFM modulation (max 50 mA)	
8	RO	0	Sets modulation used by DCDC1: 0: PWM modulation (max 700 mA) 1: PFM modulation (max 50 mA)	
7:6	RO	-	Reserved	
5	RO	0	Set to 1 to enable VOUT6 (IO supply).	
4	RO	0	Set to 1 to enable LDO5 (core PLL supply).	
3:2	RO	-	Reserved	
1	RO	0	Set to 1 to enable DCDC2 (analogue supply).	
0	RO	0	0 Set to 1 to enable DCDC1 (core supply).	

0x24: Power sequence status

J.11 DCDC control: 0x2C

This register controls the two DC-DC converters.

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M JTAG, xSCOPE and Debugging

If you intend to design a board that can be used with the XMOS toolchain and xTAG debugger, you will need an xSYS header on your board. Figure 51 shows a decision diagram which explains what type of xSYS connectivity you need. The three subsections below explain the options in detail.



M.1 No xSYS header

The use of an xSYS header is optional, and may not be required for volume production designs. However, the XMOS toolchain expects the xSYS header; if you do not have an xSYS header then you must provide your own method for writing to flash/OTP and for debugging.

M.2 JTAG-only xSYS header

The xSYS header connects to an xTAG debugger, which has a 20-pin 0.1" female IDC header. The design will hence need a male IDC header. We advise to use a boxed header to guard against incorrect plug-ins. If you use a 90 degree angled header, make sure that pins 2, 4, 6, ..., 20 are along the edge of the PCB.

Connect pins 4, 8, 12, 16, 20 of the xSYS header to ground, and then connect:

- ▶ TDI to pin 5 of the xSYS header
- TMS to pin 7 of the xSYS header
- TCK to pin 9 of the xSYS header
- DEBUG_N to pin 11 of the xSYS header